

## CLAIMS

(As Amended under PCT Article 34)

1. (Deleted)

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2. A method of cutting a lead terminal for a package type electronic component which comprises an element such as a semiconductor chip packaged in a molded part made of a synthetic resin with the lead terminal for said element projecting out of the molded part, the method comprising the steps of:

indenting a main cutting notch on at least one of obverse and reverse surfaces of the lead terminal in a step before molding the molded part while leaving an unnotched portion between the main notch and each longitudinal side surface of the lead terminal, then indenting a cutting sub-notch at the unnotched portion in a step after molding the molded part, and then cutting the lead terminal at the main notch and the sub-notch.

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3. (Amended) The lead terminal cutting method for a package type electronic component according to claim ~~1~~ or 2, wherein the lead terminal extends outwardly along a bottom surface of the molded part, the one surface of the lead terminal on which the main notch or the combination of the main notch and the sub-notch is provided is

located on the side of the bottom surface of the molded part.

4. (Deleted)

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5. The lead terminal cutting method for a package type electronic component according to claim 2, further comprising a step of implementing a metal plating treatment with respect to the lead terminal at least  
10 between the step of indenting the sub-notch and the step of cutting the lead terminal.

6. The lead terminal cutting method for a package type electronic component according to claim 2, further  
15 comprising a step of implementing a first metal plating treatment with respect to with respect to the lead terminal at least between the step of indenting the main notch and the step of cutting the lead terminal, and a step of implementing a second metal plating treatment  
20 with respect to the lead terminal at least between the step of indenting the sub-notch and the step of cutting the lead terminal.

7. (Amended) The lead terminal cutting method for a  
25 package type electronic component according to claim 4-or 5, wherein the metal plating treatment includes plating

with nickel as an underlayer and plating with a metal having good solderability over the underlayer.

8. The lead terminal cutting method for a package type  
5 electronic component according to claim 6, wherein the first metal plating treatment includes plating with nickel as an underlayer followed by plating with a metal having good solderability over the underlayer, and the second plating processing including plating with a metal  
10 having solderability.